University of York

EMBEDDED SYSTEMS DESIGN & IMPLEMENTATION OPEN INDIVIDUAL ASSESSMENT

Open Assessment 1

Examination number:

Y3606797

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1 Part 1 - Theory

1.1 Question 1

We can determine the rate X of actor H by producing a set of simultaneous equations from Table 1 and the provided Synchronous Dataflow model.

The topology matrix for the SDF model is as follows:

$$\Gamma = \begin{bmatrix} 2 & 0 & 0 & 0 & -2 & 0 & 0 & 0 & 0 \\ 0 & 2 & 0 & 0 & -2 & 0 & 0 & 0 & 0 \\ 0 & 0 & 2 & 0 & -2 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 2 & -2 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 2 & -6 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 1 & 0 & 0 & -1 \\ 0 & 0 & 0 & 0 & 0 & 0 & 3 & -2 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & X & -3 \\ 0 & 0 & 0 & 0 & 0 & 0 & -1 & 0 & 1 \end{bmatrix}$$

This gives us the following simultaneous equations:

$$2A - 2E = 0$$
 $2B - 2E = 0$ $2C - 2E = 0$
 $2D - 2E = 0$ $2E - 6F = 0$ $F - I = 0$
 $3G - 2H = 0$ $XH - 3I = 0$ $I - G = 0$

Using these equations I determined that X = 2. Similarly, I determined the firing frequencies of the remaining actors, seen in the vector q:

$$\begin{array}{cccc}
A & 6 \\
B & 6 \\
C & 6 \\
D & 6 \\
F & 2 \\
G & 2 \\
H & 3 \\
I & 2
\end{array}$$

1.2 Question 2

Using the firing frequencies determined in Question 1, I was able to identify the following PASS schedule:

```
a.fire(3); b.fire(3); c.fire(3); d.fire(3); e.fire(3); f.fire(1); a.fire(3); b.fire(3); c.fire(3); d.fire(3); f.fire(1); g.fire(2); h.fire(3); i.fire(2);
```

The maximum required FIFO buffer size is 6 as required and the number of firings of the actors match up with their frequencies in the vector q (Question 1).

1.3 Question 3

For my chosen PASS schedule the number of tokens that must be initially stored in the buffer of the feedback channel c9 is 2.

2 Part 2 - WSN MAC layer protocol

- 2.1 Question 1
- 2.2 Question 2
- 3 Part 3 Embedded platform modelling
- 3.1 Question 1